# 2-103168-8 - ACTIVE

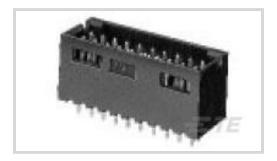
### AMPMODU | AMPMODU Headers

TE Internal #: 2-103168-8 PCB Mount Header, Vertical, Board-to-Board, 60 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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# PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **60** 

Number of Rows: 2

### Features

### **Product Type Features**

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

| Connector & Contact | Terminates To |
|---------------------|---------------|
|---------------------|---------------|

Printed Circuit Board

### **Configuration Features**

| Connector Contact Load Condition      | Fully Loaded    |
|---------------------------------------|-----------------|
| PCB Mount Orientation                 | Vertical        |
| Number of Positions                   | 60              |
| Number of Rows                        | 2               |
| Board-to-Board Configuration          | Parallel        |
| Electrical Characteristics            |                 |
| Insulation Resistance                 | 5000 MΩ         |
| Dielectric Withstanding Voltage (Max) | 750 Vrms        |
| Body Features                         |                 |
| Connector Profile                     | Standard        |
| Primary Product Color                 | Black           |
| Contact Features                      |                 |
| Mating Square Post Dimension          | .64 mm[.025 in] |

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| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] |
|---|-------------------------------|
| Contact Shape & Form                                    | Square                        |
| Contact Underplating Material                           | Nickel                        |
| PCB Contact Termination Area Plating Material           | Tin-Lead                      |
| Contact Base Material                                   | Phosphor Bronze               |
| Contact Mating Area Plating Material                    | Gold                          |
| Contact Mating Area Plating Material Thickness          | .762 μm[30 μin]               |
| Contact Type  | Pin                           |
| Contact Current Rating (Max)                            | 3 A                           |
| Termination Features                                    |                               |
| Square Termination Post & Tail Dimension                | .64 mm[.025 in]               |
| Termination Post & Tail Length                          | 3.18 mm[.125 in]              |
| Termination Method to Printed Circuit Board             | Through Hole - Solder         |
| Mechanical Attachment                                   |                               |
| Mating Retention  | With                          |
| Mating Retention Type                                   | Detent Window                 |
| Mating Alignment  | With                          |
|   |                               |

| Mating Alignment Type       | Polarization               |
|-----------------------------|----------------------------|
| PCB Mount Retention         | Without                    |
| PCB Mount Alignment         | Without                    |
| Connector Mounting Type     | Board Mount                |
| Housing Features            |                            |
| Centerline (Pitch)          | 2.54 mm[.1 in]             |
| Housing Material            | Thermoplastic              |
| Dimensions                  |                            |
| Row-to-Row Spacing          | 2.54 mm[.1 in]             |
| PCB Thickness (Recommended) | 1.4 mm[.055 in]            |
| Usage Conditions            |                            |
| Housing Temperature Rating  | Standard                   |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
| Operation/Application       |                            |
| Circuit Application         | Signal                     |

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#### **Industry Standards**

| Agency/Standard  |  |
|--|--|
|  | CSA  |
| Approved Standards   | CSA LR7189, UL E28476  |
| UL Flammability Rating   | UL 94V-0   |
| Packaging Features   |  |
| Packaging Quantity   | 24   |
| Packaging Type   | Tray   |
|  |  |
| For compliance documentation, visit the product page on TE.com>  |  |
| ELL RoHS Directive 2011/65/ELL   | Not Compliant  |
| EU RoHS Directive 2011/65/EU   | Not Compliant  |
| EU RoHS Directive 2011/65/EU<br>EU ELV Directive 2000/53/EC<br>China RoHS 2 Directive MIIT Order No 32, 2016 | Not Compliant<br>Not Compliant<br>Restricted Materials Above Threshold |

handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Do not eat, drink or smoke when using this product. Wash thoroughly after

#### Halogen Content

Solder Process Capability

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Wave solder capable to 240°C

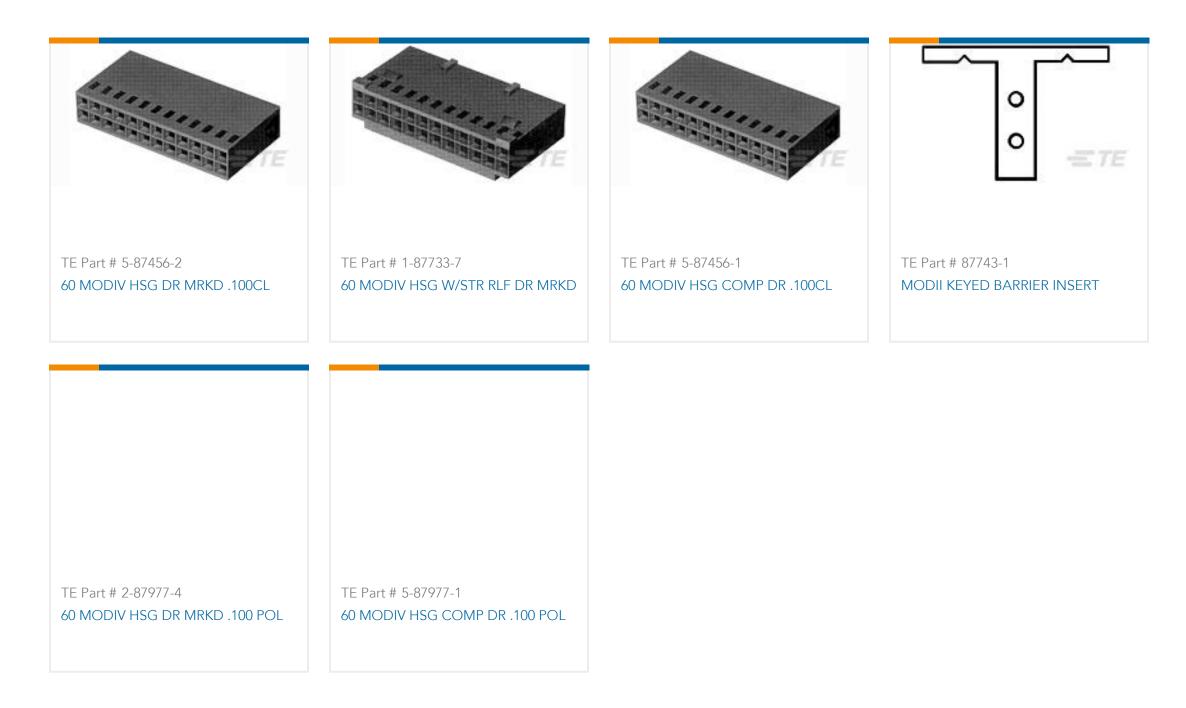
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

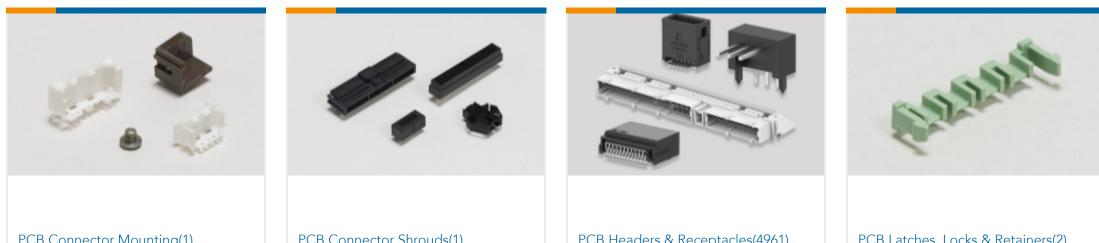
# **Compatible Parts**

PCB Mount Header, Vertical, Board-to-Board, 60 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

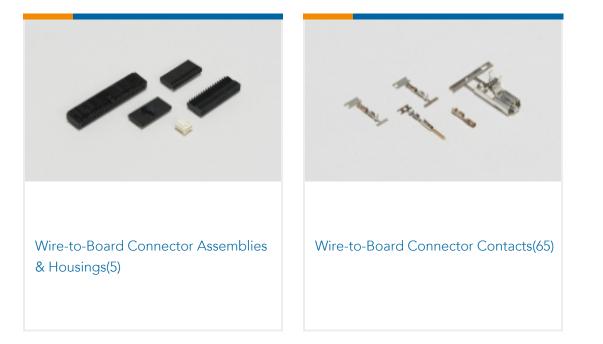




# Also in the Series AMPMODU Headers



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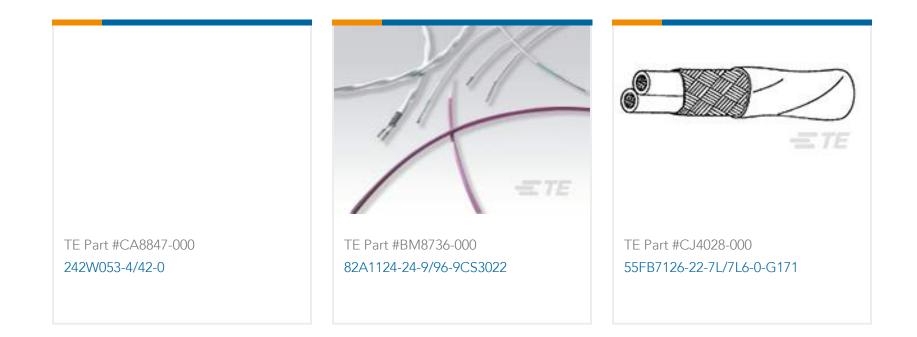


# Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 60 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





# Documents

# Product Drawings 60 MODII HDR DRST SHRD .100CL

English

#### **CAD** Files

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2-103168-8\_M.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_2-103168-8\_M.3d\_igs.zip

English

Customer View Model

# ENG\_CVM\_CVM\_2-103168-8\_M.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Product Specification

English